

ABSTRACT OF THE DISCLOSURE

A substrate treating apparatus for performing etching treatment of a plurality of substrates by immersing the substrates collectively in a heated phosphoric acid solution.

- 5 When the substrates are fetched from a container, a substrate counting mechanism and a substrate counter count the substrates to be treated collectively. A processing time determining unit determines a processing time according to a count of the substrates, by referring to a relationship
- 10 between count of substrates and processing time stored in a storage unit. Since the processing time is adjusted according to the number of substrates in a lot to be treated collectively, variations in the amount of etching are suppressed even when the number of substrates differs from one lot to
- 15 another.